





NPN/PNP POWER TRANSISTORS

NPN BD243 A/B/C PNP BD244 A/B/C



TO-220

TO-220 Plastic Package RoHS compliant

FEATURES:

- 1. Complementary Silicon Transistors.
- 2. This product is available in AEC-Q101 Compliant and PPAP Capable also.

Note: For AEC-Q101 compliant products, please use suffix -AQ in the part number while ordering.

APPLICATIONS:

- 1.Switching and Amplifier
- 2. Series and Shunt Regulators
- 3. Driver and Output stages of Hi-Fi Amplifiers

ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C Unless otherwise specified)

PARAMETER	SYMBOL	BD243/ BD244	BD243A/ BD244A	BD243B/ BD244B	BD243C/ BD244C	UNIT
Collector Emitter Voltage	V_{CEO}	45	60	80	100	V
Collector Base Voltage	V_{CBO}	45	60	80	100	V
Emitter Base Voltage	V_{EBO}	5.0			V	
Collector Current Continuous	I _C		6.0			Α
Collector Current Peak	I _{CM}		10	0.0		Α
Base Current	I _B		2.	.0		Α
Power Dissipation upto Tc=25°C	В		6	5		W
Derate above 25°C	P_{D}		0.	.5		W/°C
Power Dissipation upto Ta=25°C			2.	.0		W
Derate above 25°C	P_{D}		16	5.0		mW/°C
Storage Temperature	T_{stg}		-65 to	+150		°C
Operating Junction Temperature	Tj	150		°C		
THERMAL RESISTANCE						
Junction to Case	R _{th (j-c)}	1.92			°C/W	
Junction to Ambient in free air	R _{th (j-a)}	62.5			°C/W	







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ELECTRICAL CHARACTERISTICS at (Ta = 25 °C Unless

PARAMETER	SYMBOL	TEST CONDITION	MIN	MAX	UNIT	
Collector Cut off Current	I _{CEO}	$V_{CE} = V_{CEO(max)}, V_{BE} = 0$		0.4	mA	
Emitter Cut off Current	I _{EBO}	$V_{EB}=5V$, $I_{C}=0$		1.0	mA	
DC Current Gain	h _{FE} 1	$I_C=0.3A$, $V_{CE}=4V$	30			
DC Current Gain	''FE	$I_C=3A$, $V_{CE}=4V$	15			
Collector Emitter Saturation	V 1	I _C =6A, I _B =1A		1.5	V	
Voltage	V _{CE (sat)} 1	IC-OA, IB-IA		1.0	V	
Base Emitter on Voltage	$V_{\rm BE(on)}^{1}$	$I_C=6A, V_{CE}=4V$	-	2.0	V	
DYNAMIC CHARACTERISTIC						
Small Signal Current Gain	h _{fe}	I_C =0.5A, V_{CE} =10V, f=1KHz	20			
Transition Frequency	f_T^2	I_C =0.5A, V_{CE} =10V, f=1KHz	3		MHz	
SWITCHING CHARACTERISTICS						
Turn On Time	ton	Vcc=30V, Ic=6A, I _{B1} =I _{B2} =0.6A	0.3 (Тур.)	μS	
Turn Off Time	toff	VCC-30V, IC-0A, I _{B1} -I _{B2} -0.0A	0.6 (Typ.)		μS	

Note:

- 1. Pulse Test : Pulse width <300ms, Duty Cycle <2%
- 2. $f_T = /h_{fe}/f_{test}$
- 3. For PNP devices, the volage and current values are negative (-).



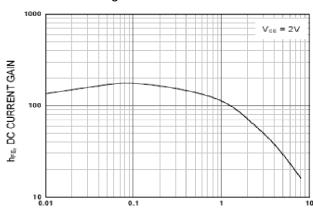




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TYPICAL CHARACTERISTIC CURVES

Figure 1. DC current Gain

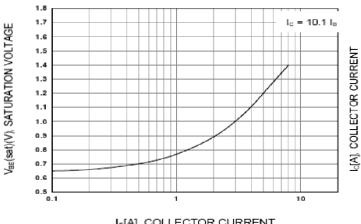


Ic[A], COLLECTOR CURRENT

Figure 3. Collector-Emitter Saturation Voltage $I_c = 10.1 I_B$ VBE(sat)(V), SATURATION VOLTAGE

Ic[A], COLLECTOR CURRENT

Figure 2. Base-Emitter Saturation Voltage



I_c[A], COLLECTOR CURRENT

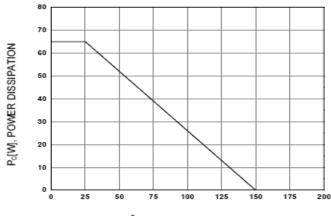
Figure 4. Safe Operating Area 100 10 10μs 100μ s

 $V_{\text{CE}}[V]$, COLLECTOR-EMITTER VOLTAGE

BD243A BD243B BD243C

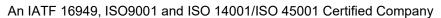


0.1



T[°C], CASE TEMPERATURE



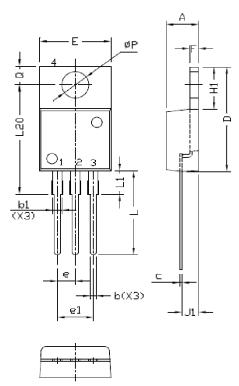






PACKAGE DETAILS

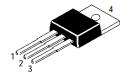
TO-220 Plastic Package



DIMENSIONS (mm)					
REF DIM	MIN	NDM	MAX	NOTES	
Α	4.47		4.67		
ю	0.70		0.91		
b1	1.17		1.37		
_	0.31		0.53		
D	14.60		15.70		
E	9.96		10.36		
е		2.54			
e1	4.98	5.08	5.18		
F	1.17		1.37		
H1	6.10		6.80		
J1	2.52		2.82		
L	12.70		13.80		
L1	3.20		3.96		
L20	15.21		16.77		
øΡ	3.73		3,96		
Q	2.59		2.89		

Pin Configuration

- 1. Base
- 2. Collector
- 3. Emitter
- 4. Collector

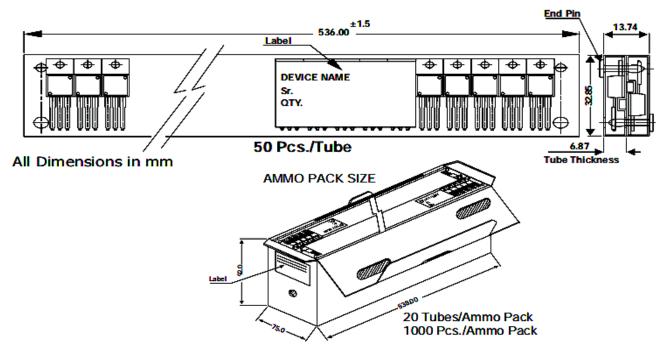






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TO-220 Tube Packing



Packing Detail

PACKAGE	STANDA	ARD PACK INNER CARTON		N BOX	OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	GrWt
TO-220	200 pcs/polybag	396 gm/200 pcs	3'x7.5'x7.5'	1.0K	17"x15"x135"	16.0K	36 kgs
	50 pcs/tube	120 gm/50 pcs	35'x37"x215"	1.0K	19" x 19" x 19"	10.0K	29 kgs





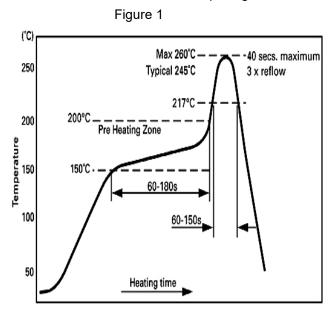


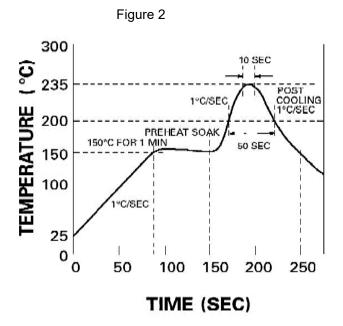
Recommended Reflow Solder Profiles

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.





Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat		
– Temperature Range	150-170°C	150-200°C
– Time	60-180 seconds	60-180 seconds
Time maintained above:		
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max.





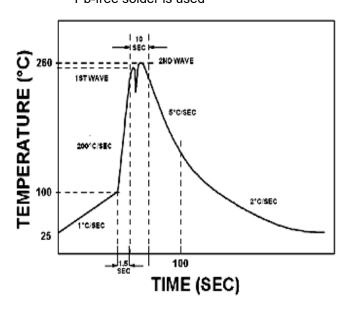


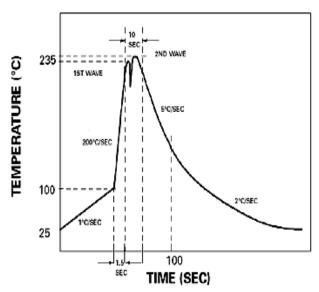
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Recommended Wave Solder Profiles

The Recommended solder Profile For Devices
with Pb-free terminal plating where a Pb-free solder is used

The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder





Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	10 seconds
Ramp-Down Rate	5°C/second max.	5°C/second max.







Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level				
Level	Time	Condition		
1	Unlimited	≤30 °C / 85% RH		
2	1 Year	≤30 °C / 60% RH		
2a	4 Weeks	≤30 °C / 60% RH		
3	168 Hours	≤30 °C / 60% RH		
4	72 Hours	≤30 °C / 60% RH		
5	48 Hours	≤30 °C / 60% RH		
5a	24 Hours	≤30 °C / 60% RH		
6	Time on Label(TOL)	≤30 °C / 60% RH		







Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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